

REFLOW SOLDER SYSTEMS AND OVENS (3.2018)

for several reflow solder processes, voidfree, without flux



Model

max. substrate size

T_{max}

T °C continuous at
optional

Ramp up rate

Vacuum up to

Flowmeter

Controller

Dimension (WxDxH)

RSS-110-S

110 x 110mm

400 °C (*)

400 °C

500 °C (Cu plate)

120 K/min

10^{-3} hPa

MFC

SIMATIC®

260x420x220mm

RSS-160-S

160 x 160mm

400 °C (*)

400 °C

500 °C (Cu plate)

100 K/min

10^{-3} hPa

MFC

SIMATIC®

300x420x220mm

RSS-210-S

210 x 210 mm

400 °C (*)

400 °C

500 °C (Cu plate)

240 K/min

10^{-3} hPa (*)

MFC

SIMATIC®

643x480x310mm